

5. [(New)] (amended) A stacked semiconductor chip package comprising:

a substrate;

a first chip[, mounted] on the substrate and electrically connected to the substrate by a plurality of electrical leads;

a second chip[,] electrically connected to the substrate by a plurality of electrical leads and having two opposed longitudinal sides defining a first length; and

a plate[, mounted] between the first chip and the second chip, [and] connected to the first chip and the second chip, [corresponding to the two longitudinal sides of the second chip, the plate] and having two opposed longitudinal sides corresponding to the two longitudinal sides of the second chip defining a second length, the second length being larger than the first length to expose the opposed longitudinal sides of the plate.